

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	266	156/260	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 12:18
L2	338	156/261	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 12:18
L3	137	156/262	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 12:18
L4	365	156/263	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 12:18
L5	496	156/259	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 12:19
L6	1827	156/324	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 12:19
L7	2471	156/344	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 12:19
L8	801	156/353	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 12:19
L9	847	156/358	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 12:19
L10	1619	156/361	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 12:19
L11	520	156/391	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 12:19
L12	474	156/512	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 12:19

L13	930	156/517	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 12:19
L14	447	156/518	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 12:19
L15	277	156/520	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 12:19
L16	1051	156/521	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 12:19
L17	154	156/537	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 12:19
L18	866	156/538	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 12:19
L19	2087	156/580	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 12:19
L20	1863	156/584	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 12:19
L21	2859	156/247	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 12:19
L22	1491	156/256	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 12:20
L23	5237	tape and (cutter or blade or knife) and frame and (chip or die or semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 12:21
L24	1522	(tape same (cutter or blade or knife)) and frame and (chip or die or semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 12:21

S1	77	(("3788572") or ("4704304") or ("5475918") or ("5504373") or ("5696033") or ("5715143") or ("5723907") or ("5729049") or ("5789803") or ("5952611") or ("5953216") or ("5998860") or ("6012502") or ("6013535") or ("6016004") or ("6017776") or ("6021563") or ("6023666") or ("6025212") or ("6048755") or ("6051449") or ("6060339") or ("6080263") or ("6084311") or ("6091136") or ("6091140") or ("6098278") or ("6110805") or ("6111324") or ("6201299") or ("6218731") or ("6265766") or ("6301121") or ("6303997") or ("6326700") or ("6331451") or ("6340525") or ("6423407") or ("6489218")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/03/18 10:37
S2	18	casey near2 Prindiville	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 10:37

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	29	"wire bond slot"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 15:12
L2	19	"wire bond slot" and tape	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 15:12
L3	5	"wire bonding slot" and tape	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 15:12
L4	82246	wire near2 bond\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 15:13
L5	12532	(wire near2 bond\$4) and tape	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 15:13
L6	1056	(wire near2 bond\$4) and tape and percentage	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 15:13
L7	329	(wire near2 bond\$4) and tape and percentage and slot	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 15:15
L8	9	(wire near2 bond\$4) and ((tape or film or sheet) same (percentage same slot))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 15:14
L9	299	(wire near2 bond\$4) and tape and percentage and slot and (support or frame)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 15:15
L10	272	(wire near2 bond\$4) and tape and percentage and slot and (support or frame) and (die or chip or semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 15:20
L11	267	(wire near2 bond\$4) and tape and percentage and slot and (support or leadframe) and (die or chip or semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 15:21
L12	3	(wire near2 bond\$4) and tape and percentage and slot and (leadframe) and (die or chip or semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 15:22

L13	6	tape and percentage and slot and (leadframe) and (die or chip or semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 15:22
L14	192	tape and slot and (leadframe) and (die or chip or semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 15:23
L15	44	(tape same slot) and (leadframe) and (die or chip or semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 15:25
L16	4	((tape same slot) same (leadframe)) and (die or chip or semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/03/18 15:26